Claim 2. (Original) The surface laminar circuit board of claim 1, wherein said dielectric layer is a photosensitive dielectric layer.

Claim 3. (Original) The surface laminar circuit board of claim 2, wherein said photosensitive dielectric layer is in direct contact with the insulating layer by way of the hole, and wherein said conductive pad is disposed directly on an upper surface of said photosensitive dielectric layer, said dielectric layer separating said conductive pad from said conductive layer and from said insulating layer.

Claim 4. (Original) The surface laminar circuit board of claim 2, wherein said conductive pad is disposed within the hole, and is in direct contact with the insulating layer.

Claim 5. (Original) The surface laminar circuit board of claim 1, wherein said insulating layer is an FR4 insulating layer.

Claim 6. (Amended) The surface laminar circuit board of claim 1, wherein said conductive layer comprises a [signal] ground layer.

Claim 7. (Amended) The surface laminar circuit board of claim 6, wherein said [signal] ground layer is comprised of copper.

Claim 8. (Original) The surface laminar circuit board of claim 1, wherein said hole is formed by etching.

Claim 9. (Original) The surface laminar circuit board of claim 2, wherein said photosensitive dielectric layer has a thickness, in a region over the conductive layer, less than about 50 micrometers.

Claim 10. (Original) The surface laminar circuit board of claim 2, wherein said photosensitive dielectric layer has a thickness, in a region over the conductive layer, equal to or less than about 40 micrometers.

Claim 11. (Original) The surface laminar circuit board of claim 2, further comprising signal traces disposed directly on said photosensitive dielectric layer.

Claim 12. (Original) The surface laminar circuit board of claim 1, wherein said conductive pad is disposed completely within the area defined by the outer periphery of the hole.

Claims 13-~~20~~ 19 (Previously Cancelled).

Claim 20. (Amended) A surface laminar circuit board, comprising:

an insulating layer;

a [signal] ground conductive layer disposed on an upper surface of said insulating layer, said conductive layer having a hole formed therein;

a photosensitive dielectric layer disposed on an upper surface of the [signal] ground conductive layer, said dielectric layer having a photo micro-via formed therein;

a signal trace disposed on said photosensitive dielectric layer, and being electrically coupled with said [signal] ground conductive layer by way of said photo micro-via;

a conductive pad having [a majority] <u>over 50%</u> thereof within an area defined by an outer periphery of the hole, and being electrically coupled with said signal trace; and

a surface mounted component mounted on said conductive pad.

Claim 21. (Original) The surface laminar circuit board of claim 20, wherein said photosensitive dielectric layer is in direct contact with the insulating layer by way of the hole, and wherein said conductive pad is disposed directly on an upper surface of said photosensitive dielectric layer, said dielectric layer separating said conductive pad from said conductive layer and from said insulating layer.

Claim 22. (Original) The surface laminar circuit board of claim 20, wherein said conductive pad is disposed within the hole, and is in direct contact with the insulating layer.

Claim 23. (Previously Added) A surface laminar circuit board, comprising:

an insulating layer;

a sheet of conductive material disposed on an upper surface of said insulating layer, said sheet of conductive material having a hole formed therein, the hole exposing a portion of said insulating layer, the sheet of conductive material completely surrounding an area defined by the hole, the area being in registration with, and corresponding in shape and size, to the portion of said insulating layer exposed by the hole;

a dielectric layer disposed on an upper surface of said conductive material; and

a conductive pad having a major portion thereof disposed directly over the portion of said insulating layer exposed by the hole, said conductive pad being for receiving a surface mounted component thereon.

Claim 24. (Previously Added) The surface laminar circuit board of claim 23, wherein said dielectric layer is in direct contact with the portion of said insulating layer exposed by the hole, and wherein said conductive pad is disposed in direct contact with an upper surface of said dielectric layer, said dielectric layer separating said conductive pad from said conductive material and from said insulating layer.

Claim 25. (Amended) The surface laminar circuit board of claim 23, wherein said conductive material comprises a [signal] ground layer.

Claim 26. (Previously Added) The surface laminar circuit board of claim 25, wherein said dielectric layer has a thickness, in a region over said conductive material, less than about 50 micrometers.